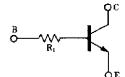


COMPOUND TRANSISTOR BA1A4Z

on-chip resistor PNP silicon epitaxial transistor For mid-speed switching

FEATURES

 On-chip bias resistor (R₁ = 10 kΩ)



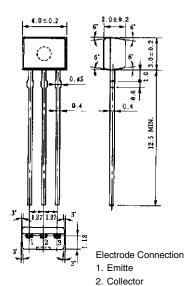
· Complementary transistor with BA1A4Z

ABSOLUTE MAXIMUM RATINGS (Ta = 25°C)

Parameter	Symbol	Ratings	Unit
Collector to base voltage	VcBO	60	V
Collector to emitter voltage	VCEO	50	V
Emitter to base voltage	VEBO	5	V
Collector current (DC)	Ic(DC)	100	mA
Collector current (Pulse)	Ic(pulse) *	200	mA
Total power dissipation	Рт	250	mW
Junction temperature	Tj	150	°C
Storage temperature	T _{stg}	-55 to +150	°C

^{*} PW \leq 10 ms, duty cycle \leq 50 %

PACKAGE DRAWING (UNIT: mm)



^{3.} Base

ELECTRICAL CHARACTERISTICS (Ta = 25°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Collector cutoff current	Ісво	$V_{CB} = 50 \text{ V}, I_E = 0$			100	nA
DC current gain	hFE1 **	$V_{CE} = 5.0 \text{ V}, \text{ Ic} = 5.0 \text{ mA}$	135	340	600	ı
DC current gain	hFE2 **	Vce = 5.0 V, Ic = 50 mA	100	300		-
Collector saturation voltage	VCE(sat) **	$I_{C} = 5.0 \text{ mA}, I_{B} = 0.25 \text{ mA}$		0.04	0.2	V
High level input voltage	VIL **	$V_{CE} = 0.2 \text{ V}, \text{ Ic} = 5.0 \text{ mA}$	2.0	0.8		٧
Low level input voltage	V _{IH} **	$V_{CE} = 5.0 \text{ V}, \text{ Ic} = 100 \ \mu\text{A}$		0.55	0.5	V
Input resistance	R ₁		0.7	10	13.0	kΩ
Turn-on time	ton	$Vcc = 5.0 \text{ V}, \text{ RL} = 1.0 \text{ k}\Omega$			0.2	μs
Storage time	tstg	$V_1 = 5.0 \text{ V}, \text{ PW} = 2.0 \ \mu\text{s}$			5.0	μs
Turn-off time	toff	duty cycle≤2 %			6.0	μs

^{**} Pulse test PW \leq 350 μ s, duty cycle \leq 2 %

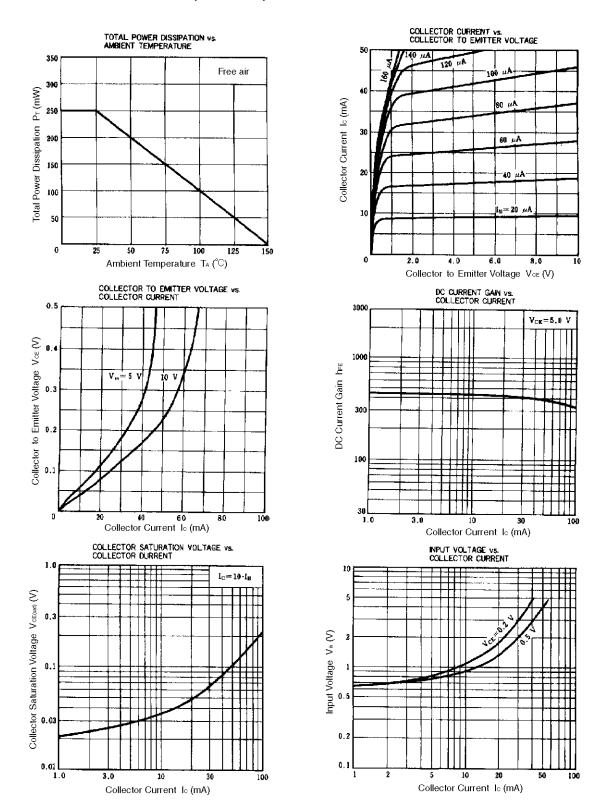
hfe CLASSIFICATION

Marking	Q	Р	K
h _{FE1}	135 to 270	200 to 400	300 to 600

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TYPICAL CHARACTERISTICS (Ta = 25°C)





[MEMO]

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